

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSC0923NDI	**Issued**	03. May 2021
MA#	MA001013780		
Package	PG-TISON-8-2	**Weight***	96.56 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	0.393	0.41	0.41	4065	4065
chip_2	inorganic material	silicon	7440-21-3	0.210	0.22	0.22	2179	2179
leadframe	inorganic material	phosphorus	7723-14-0	0.010	0.01		106	
	non noble metal	zinc	7440-66-6	0.041	0.04		425	
	non noble metal	iron	7439-89-6	0.822	0.85		8509	
	non noble metal	copper	7440-50-8	33.360	34.55	35.45	345491	354531
wire	noble metal	gold	7440-57-5	0.062	0.06	0.06	640	640
encapsulation	organic material	carbon black	1333-86-4	0.096	0.10		989	
	plastics	epoxy resin	-	4.920	5.10		50955	
	inorganic material	silicondioxide	60676-86-0	42.753	44.28	49.48	442760	494704
leadfinish	non noble metal	tin	7440-31-5	1.108	1.15	1.15	11474	11474
plating	noble metal	silver	7440-22-4	0.186	0.19	0.19	1924	1924
solder	non noble metal	tin	7440-31-5	0.020	0.02		205	
	noble metal	silver	7440-22-4	0.025	0.03		257	
	non noble metal	lead	7439-92-1	0.947	0.98	1.03	9808	10270
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.003			36	
	non noble metal	zinc	7440-66-6	0.014	0.01		144	
	non noble metal	iron	7439-89-6	0.279	0.29		2885	
	non noble metal	copper	7440-50-8	11.312	11.71	12.01	117148	120213
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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